



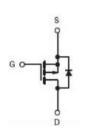
MJ P-Channel Enhancement Mode Power MOSFET

Description

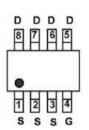
The MJ30P12S uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

- V_{DS} =-30V,I_D =-12A
 R_{DS(ON)} <25mΩ @ V_{GS}=-4.5V
 R_{DS(ON)} <15mΩ @ V_{GS}=-10V
- High power and current handing capability
- Lead free product is acquired
- Surface Mount Package



Schematic diagram



Application

Load switch

PWM applications

Power management



Marking and pin assignment

SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ30P12S	MJ30P12S	SOP-8	Ø330mm	12mm	4000 units

Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	-30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous (Tc =25°C)	lo	-12	А
Drain Current-Continuous (Tc =100℃)	lo	-8.4	А
Drain Current -Pulsed (Note 1)	Ідм	-48	А
Maximum Power Dissipation (Tc =25°C)	Po	3	W
Maximum Power Dissipation (Tc =100°C)	Po	1.3	°C
Single pulse avalanche energy (Note 5)	Eas	231	mJ
Operating Junction and Storage Temperature Range	TJ ,TSTG	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	Reja	41.67	°C/W	
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Parameter Symbol Condition		Min	Тур	Max	Unit
Off Characteristics		1	1		1	
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V,I _D =-250µA	-30	-33	-	V
Zero Gate Voltage Drain Current	loss	Vds=-30V,Vgs=0V	-	-	-1	μA
Gate-Body Leakage Current	lgss	VDS=±20V,VDS=0V	-	-	±100	nA
On Characteristics (Note 3)	I	I	1			
Gate Threshold Voltage	VGS(th)	Vos=Vgs,Io=-250µA	-1	-1.5	-3	V
		Vgs=-10V, Id=-10A	-	11.5	15	mΩ
Drain-Source On-State Resistance	Rds(on)	Vgs=-4.5V, Id=-7A		18	25	mΩ
Forward Transconductance	G FS	V _{DS} =-10V,I _D =-10A	-	20	-	S
Dynamic Characteristics (Note 4)		I	1	1	1	1
Input Capacitance	Ciss		-	1750	-	PF
Output Capacitance	Coss	V⊳s=-15V,V₀s=0V F=1.0MHz	-	215	-	PF
Reverse Transfer Capacitance	Crss		-	180	-	PF
Switching Characteristics (Note 4)		1	1	1	1	1
Turn-on Delay Time	td(on)		-	9	-	nS
Turn-on Rise Time	tr	V _{DD} =-15V, I _D =-10A	-	8	-	nS
Turn-Off Delay Time	td(off)	V_{GS} =-10V,R _{GEN} =1 Ω	-	28	-	nS
Turn-Off Fall Time	tr		-	10	-	nS
Total Gate Charge	Qg		-	24	_	nC
Gate-Source Charge	Qgs	V _{DS} =-15V,I _D =-10A V _{GS} =-10V	-	3.5	_	nC
Gate-Drain Charge	Qgd		-	6	-	nC
Drain-Source Diode Characteristics	I	<u> </u>		1	I	1
Diode Forward Voltage (Note 3)	Vsd	Vgs=0V,Is=-12A	-	-	-1.2	V
Diode Forward Current (Note 2)	ls		_	_	-12	A

Notes:

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② Surface Mounted on FR4 Board, t ≤ 10 sec.

③ Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

(4) Guaranteed by design, not subject to production

(5) Eas condition: Tj=25°C, V_DD=-15V, V_G=10V, L=0.5mH, Rg=25\Omega, Ias=-34A





150

50

Typical Electrical and Thermal Characteristics

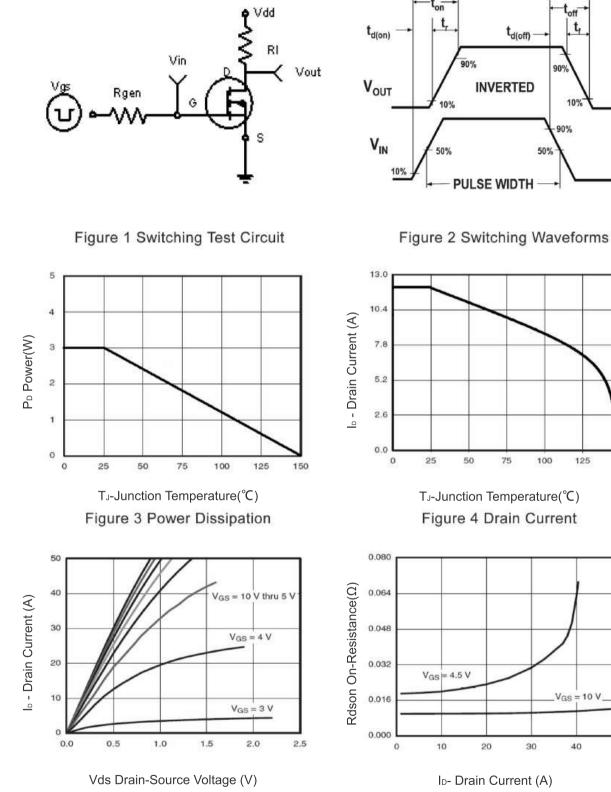


Figure 5 Output Characteristics

Figure 6 Drain-Source On-Resistance







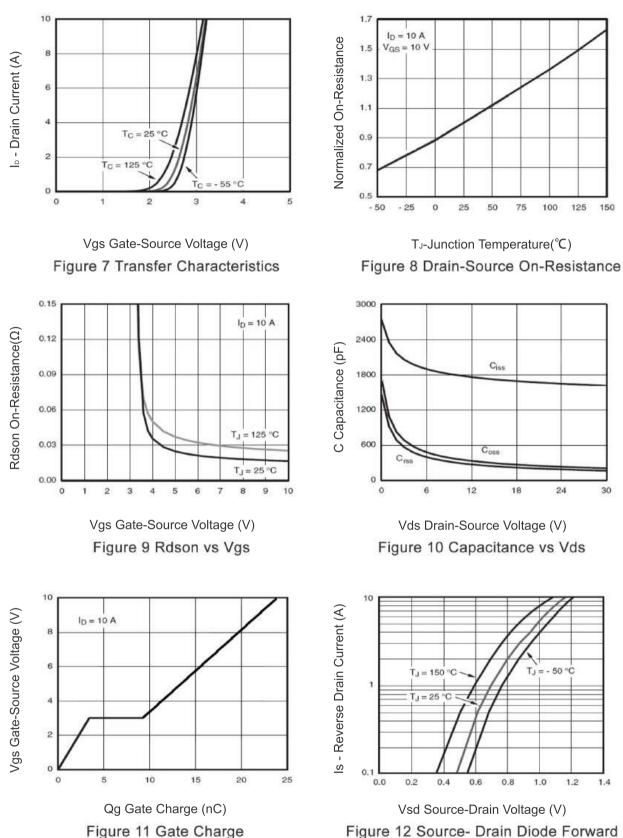
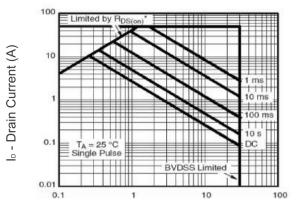


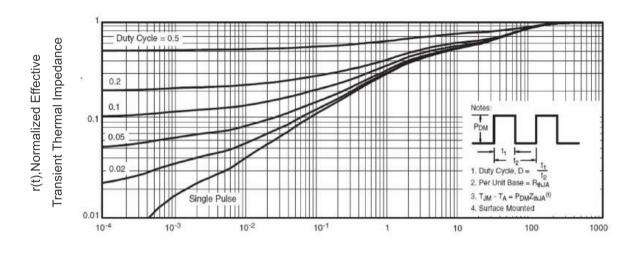
Figure 12 Source- Drain Diode Forward







Vds Drain-Source Voltage (V) Figure 13 Safe Operation Area

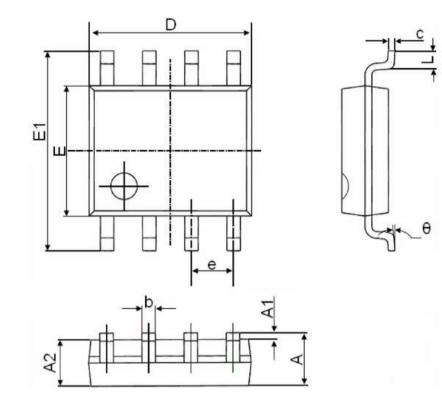


Square Wave Pluse Duration(sec) Figure 14 Normalized Maximum Transient Thermal Impedance





SOP-8 Package Information



Compleal.	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
с	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	1.270(BSC)		(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	





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